A. Interconnect & Package 분과

2021년 1월 27일(수), 14:45-16:15 / 채널 C

[WC4-A] Emerging Interconnect Ⅱ

좌장: 김병준 교수 (안동대학교), 이웅선 수석 (SK하이닉스)

WC4-A-1 **14:45-15:15**	[초청] **Mechanism of Selective Cobalt Capping Process for Copper Interconnects: A DFT Study** Romel Hidayat[1], Tanzia Chowdhury[1], Hye-Lee Kim[1], Sang-Ick Lee[2], and Won-Jun Lee[1] *[1]Departments of Nanotechnology and Advanced Materials Engineering, Sejong University, [2]DNF Co., Ltd.*
WC4-A-2 **15:15-15:30**	**Effect of Complexing Agents on Co Surface Modification for Chemical-Mechanical Polishing (CMP) and Post-CMP Cleaning Process** Jinuk Byun[1], Ohsung Kwon[2], Kyong Kyu Myong[1], KiHo Bae[3], and Jae Jeong Kim[1,4] *[1]School of Chemical and Biological Engineering, Seoul National University, [2]Department of Chemical and Biomolecular Engineering, University of Illinois at Urbana-Champaign, [3]Semiconductor R&D Center, Samsung Electronics Co., Ltd., [4]School of Chemical and Biological Engineering, Institute of Chemical Process, Seoul National University*
WC4-A-3 **15:30-15:45**	**Mechanical Planarization of Polymer Dielectrics for FOWLP** Hyeokjin Chu[1], Hyunjoo Kim[2], and Sungdong Kim[1] *[1]Department of Mechanical System Design, Seoul National University of Science and Technology, [2]Department of Chemistry & Biology, Seoul National University of Science and Technology*
WC4-A-4 **15:45-16:00**	철회
WC4-A-5 **16:00-16:15**	**Mechanism of Grain Size and Mechanical Properties of Sn-57.6Bi-0.4Ag Solder Joint by Using the Nanoindentation** Jun-Ho Jang, Kyung Deuk Min, Choong-Jae Lee, Jae-Ha Kim, Dong Gil Kang, and Seung-Boo Jung *School of Advanced Materials Science and Engineering, Sungkyunkwan University*